SDLS035A - DECEMBER 1983 - REVISED APRIL 2003

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

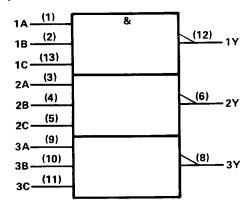
These devices contain three independent 3-input NAND gates.

The SN5410, SN54LS10, and SN54S10 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7410, SN74LS10, and SN74S10 are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

11	NPUT	s	OUTPUT
A	В	С	Υ
н	н	н	L
L	X	X	н
Х	L	×	н
X	X	L	Н

logic symbol†



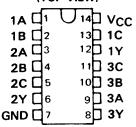
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

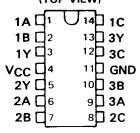
positive logic

$$Y = \overline{A \cdot B \cdot C}$$
 or $Y = \overline{A} + \overline{B} + \overline{C}$

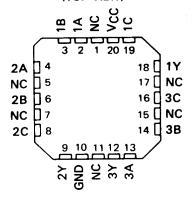
SN5410 . . . J PACKAGE
SN54LS10, SN54S10 . . . J OR W PACKAGE
SN7410 . . . N PACKAGE
SN74LS10, SN74S10 . . . D OR N PACKAGE
(TOP VIEW)



SN5410 . . . W PACKAGE (TOP VIEW)

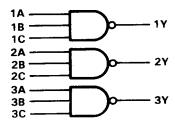


SN54LS10, SN54S10 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

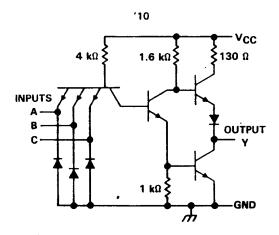
logic diagram (positive logic)

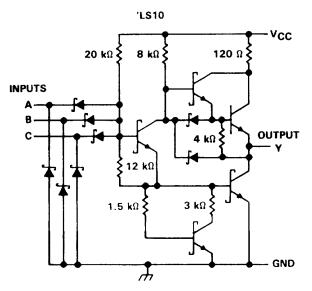


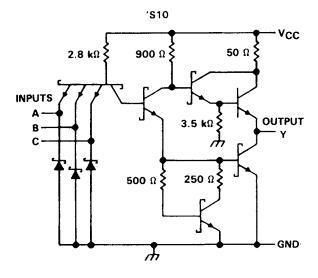


SDLS035A - DECEMBER 1983 - REVISED APRIL 2003

schematics (each gate)







Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '10, 'S10	5.5 V
'LS10	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

		SN5410			SN7410			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH High-level input voltage	2			2			V	
V _{IL} Low-level input voltage			0.8			0.8	v	
IOH High-level output current			- 0.4			- 0.4	mA	
IOL Low-level output current			16			. 16	mA	
T _A Operating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS †				SN5410				
			110431	MIN	TYP‡	MAX	MIN	TYP\$	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 12 mA				- 1.5			- 1.5	v
Vон	V _{CC} = MIN,	V _{1L} = 0.8 V,	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
l ₁	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
Чн	V _{CC} = MAX,	V ₁ = 2.4 V				40			40	μА
[‡] IL	V _{CC} = MAX,	V ₁ = 0.4 V				- 1.6			- 1.6	mA
los§	V _{CC} = MAX			- 20		- 55	- 18		- 55	mA
Iссн	V _{CC} = MAX,	V1 = 0 V			3	6		3	6	mA
¹ CCL	V _{CC} = MAX,	V ₁ = 4.5 V			9	16.5		9	16.5	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

	FROM	то					
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	A B == 0				11	22	ns
tPHL_	A, B or C	Y	$R_L = 400 \Omega$, $C_L = 15 pF$		7	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time.

SN54LS10, SN74LS10, TRIPLE 3-INPUT POSITIVE-NAND GATES

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recommended operating conditions

		,	SN54LS10			SN74LS10			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC Supply voltage		4.5	5	5.5	4.75	5	5.25	V	
VIH High-level input v	oltage	2			2			V	
VIL Low-level input ve	oltage			0.7			0.8	v	
IOH High-level output	current			- 0.4			- 0.4	mA	
IOL Low-level output	current			4			8	mA	
T _A Operating free-air	temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54LS10	SN74LS10 ·	
FARAMETER	TEST CONDITIONS 1	MIN TYP# MAX	MIN TYP# MAX	UNIT
VIK	V _{CC} = MIN, I _I = 18 mA	- 1.5	- 1.5	V
V _{ОН}	$V_{CC} = MIN$, $V_{IL} = MAX$, $I_{OH} = -0.4 \text{ mA}$	2.5 3.4	2.7 3.4	٧
Va.	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 4 mA	0.25 0.4	0.4	.,
VOL	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 8 mA		0.25 0.5	V
l ₁	V _{CC} = MAX, V ₁ = 7 V	0.1	0.1	mA
ЧН	V _{CC} = MAX, V _I = 2.7 V	20	20	μΑ
t _f L	V _{CC} = MAX, V ₁ = 0.4 V	- 0.4	- 0.4	mA
IOS\$	V _{CC} = MAX	- 20 - 100	- 20	mA
Іссн	V _{CC} = MAX, V _I = 0 V	0.6 1.2	0.6 1.2	mA
ICCL	V _{CC} = MAX, V _I = 4.5 V	1.8 3.3	1.8 3.3	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
tPLH	A, B or C	Y	$R_L = 2 k\Omega$, $C_L = 15 pF$		9	15	ns
^t PHL	,	•	п_ = 2 каг, С_ = 15 рг		10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

			SN54S10			SN74S10			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
VIH	High-level input voltage	2			2			٧	
VIL	Low-level input voltage			0.8			0.8	٧	
ЮН	High-level output current			– 1			- 1	mA	
loL	Low-level output current			20			20	mA	
TA	Operating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DARAMETER	TEGT COMPLETIONS T	SN54S10	SN74S10	UNIT
PARAMETER	TEST CONDITIONS †	MIN TYP\$ MAX	MIN TYP\$ MAX	UNII
V _{IK}	V _{CC} = MIN, I _I = -18 mA	-1.2	-1.2	٧
V _{OH}	$V_{CC} = MIN$, $V_{IL} = 0.8 \text{ V}$, $I_{OH} = -1 \text{ mA}$	2.5 3.4	2.7 3.4	٧
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 20 mA	0.5	0.5	٧
11	V _{CC} = MAX, V _I = 5.5 V	1	1	mA
Ін	V _{CC} = MAX, V _I = 2.7 V	50	50	μА
[‡] IL	V _{CC} = MAX, V _I = 0.5 V	-2	-2	mA
IOS§	V _{CC} = MAX	-4 0 -1 00	-40 -100	mA
Іссн	V _{CC} = MAX, V _I = 0 V	7.5 12	7.5 12	mA
¹ CCL	V _{CC} = MAX, V _I = 4.5 V	15 27	15 27	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COND	DITIONS	MIN	TYP	MAX	UNIT
^t PLH			R _L = 280 Ω,	C _l = 15 pF		3	4.5	ns
tPHL	A D - 0	V	H 200 12,	OL 13 bi		3	5	ns
^t PLH	A, B or C	Y	R ₁ = 280 Ω,	C: = 50 pF		4.5		ns
^t PHL			n[- 200 12,	C _L = 50 pF		5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07005BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07005BCA	Samples
JM38510/07005BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07005BDA	Samples
JM38510/30005B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005B2A	Samples
JM38510/30005BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005BCA	Samples
JM38510/30005BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005BDA	Samples
JM38510/30005SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005SDA	Samples
M38510/07005BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07005BCA	Samples
M38510/07005BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07005BDA	Samples
M38510/30005B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005B2A	Samples
M38510/30005BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005BCA	Samples
M38510/30005BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005BDA	Samples
M38510/30005SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30005SDA	Samples
SN54LS10J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS10J	Samples
SN54S10J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S10J	Samples
SN74LS10D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples
SN74LS10DG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples
SN74LS10DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples



PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS10DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples
SN74LS10N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS10N	Samples
SN74LS10NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS10	Samples
SN74S10N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S10N	Samples
SNJ54LS10FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 10FK	Samples
SNJ54LS10J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS10J	Samples
SNJ54LS10W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS10W	Samples
SNJ54S10J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S10J	Samples
SNJ54S10W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S10W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

PACKAGE OPTION ADDENDUM

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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS10, SN54LS10-SP, SN54S10, SN74LS10, SN74S10:

Catalog: SN74LS10, SN54LS10, SN74S10

Military: SN54LS10, SN54S10

Space : SN54LS10-SP

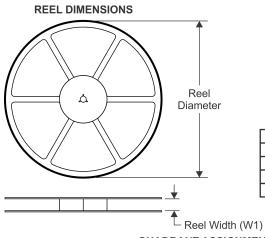
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and gualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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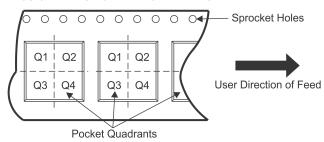
TAPE AND REEL INFORMATION





A0	
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

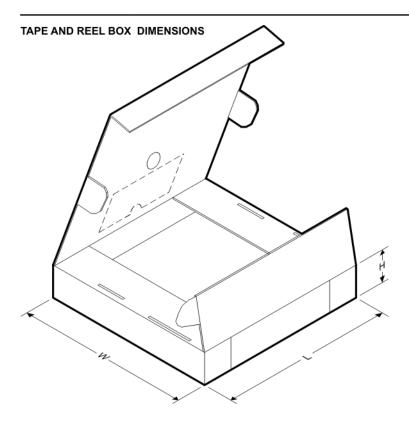
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Ī	Device		Package Drawing		SPQ	Reel Diameter	Reel Width	A0 (mm)	B0 (mm)	K0	P1 (mm)	W (mm)	Pin1 Quadrant
l		Туре	Drawing				W1 (mm)	(11111)	(11111)	(mm)	(11111)	(111111)	Quadrant
	SN74LS10DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74LS10NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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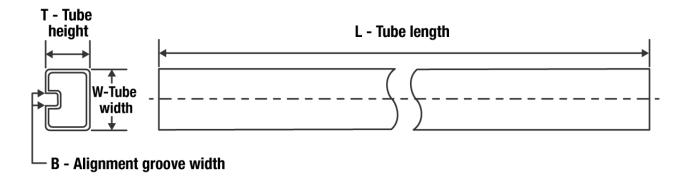
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS10DR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LS10NSR	SO	NS	14	2000	853.0	449.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE

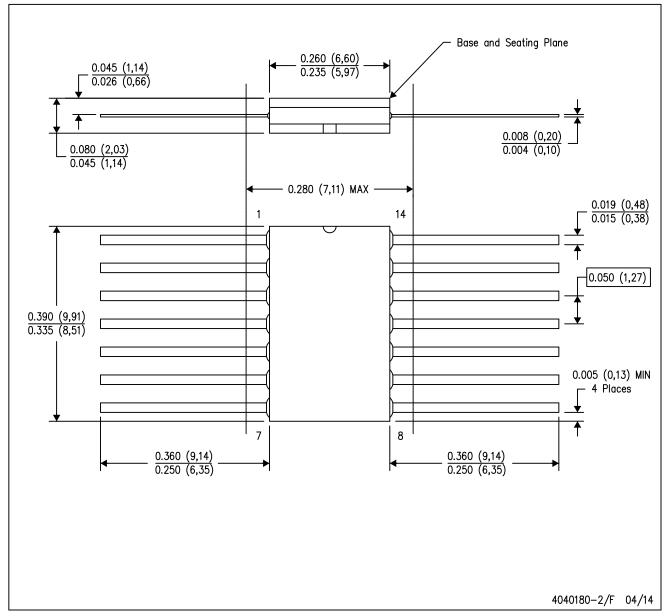


*All dimensions are nominal

ii dimensions are nomina								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/30005B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/30005B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74LS10D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS10DG4	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS10N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS10N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S10N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S10N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS10FK	FK	LCCC	20	1	506.98	12.06	2030	NA

W (R-GDFP-F14)

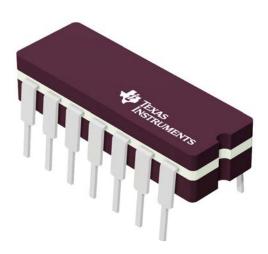
CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



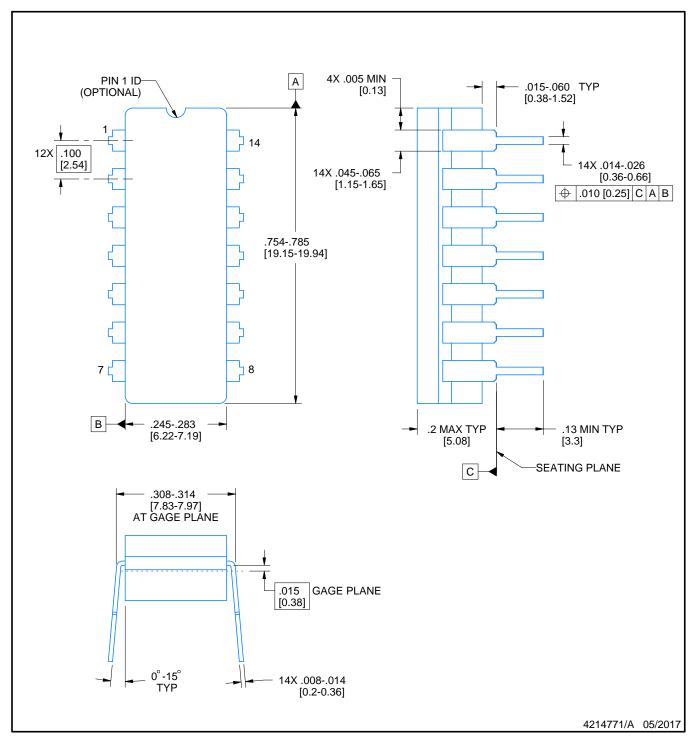
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





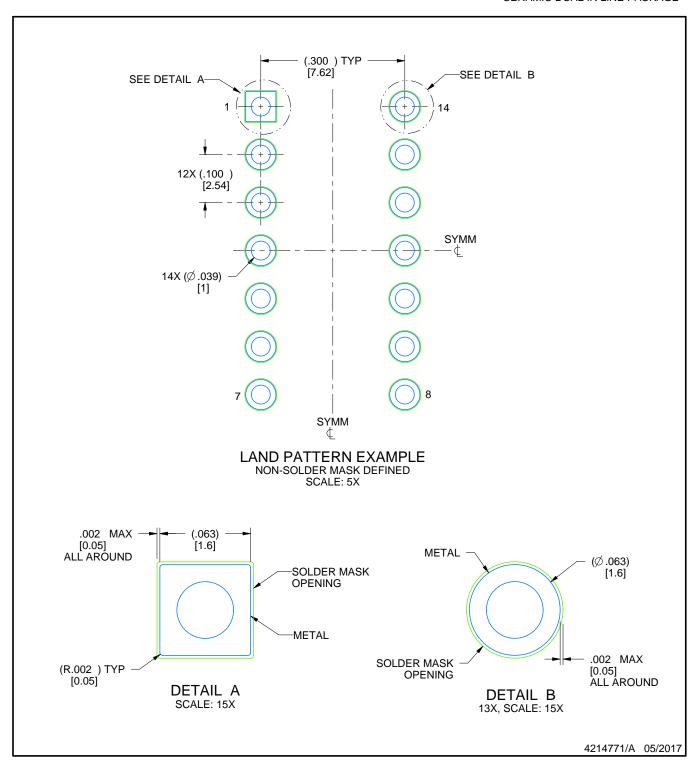
CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

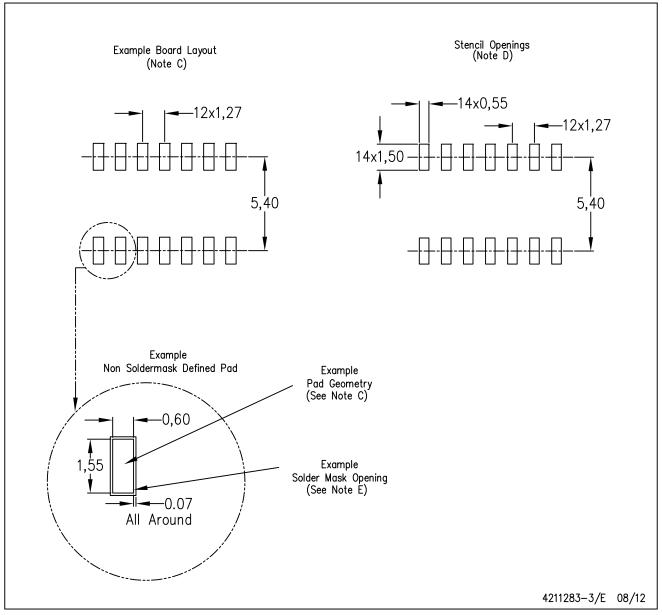


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



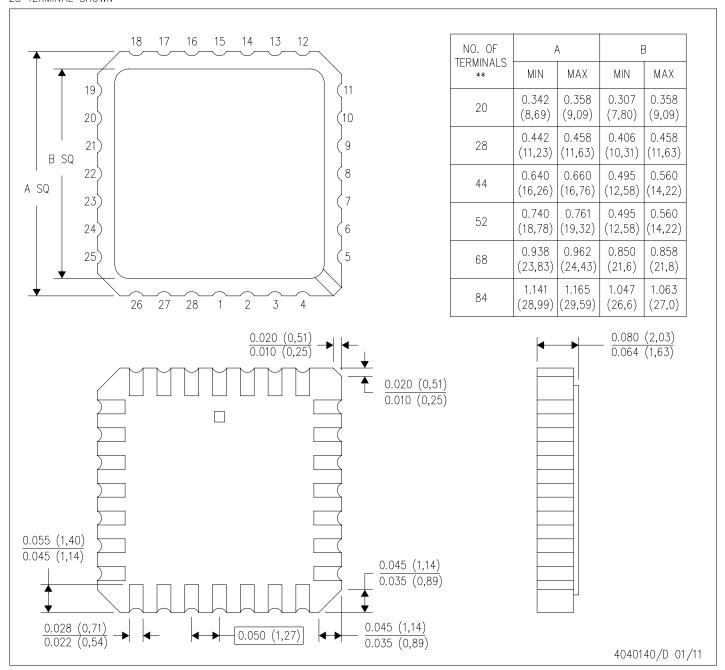
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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